

CD4724B Types

CMOS 8-Bit Addressable Latch

High-Voltage Types (20-Volt Rating)

■ CD4724B 8-bit addressable latch is a serial-input, parallel-output storage register that can perform a variety of functions.

Data are inputted to a particular bit in the latch when that bit is addressed (by means of inputs A0, A1, A2) and when WRITE DISABLE is at a low level. When WRITE DISABLE is high, data entry is inhibited; however, all 8 outputs can be continuously read independent of WRITE DISABLE and address inputs.

A master RESET input is available, which resets all bits to a logic "0" level when RESET and WRITE DISABLE are at a high level. When RESET is at a high level, and WRITE DISABLE is at a low level, the latch acts as a 1-of-8 demultiplexer; the bit that is addressed has an active output which follows the data input, while all unaddressed bits are held to a logic "0" level.

The CD4724B types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (NSR suffix), and 16-lead thin shrink small-outline packages (PW and PWR suffixes).

**RECOMMENDED FOR
NEW DESIGNS**
Features:
CD4099B

- Serial data input
- Active parallel output
- Storage register capability
- Master clear
- Can function as demultiplexer
- Standardized, symmetrical output characteristics
- 100% tested for quiescent current at 20 V
- Maximum input current of 1 μ A at 18 V (full package-temperature range), 100 nA at 18 V and 25°C.
- Noise margin (full package-temperature range) = 1 V at $V_{DD} = 5$ V, 2 V at $V_{DD} = 10$ V, 2.5 V at $V_{DD} = 15$ V
- 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of 'B' Series CMOS Devices"

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, (V_{DD})
Voltage referenced to V_{SS} Terminal) -0.5V to +20V

INPUT VOLTAGE RANGE, ALL INPUTS -0.5V to V_{DD} +0.5V

DC INPUT CURRENT, ANY ONE INPUT ± 10 mA

POWER DISSIPATION PER PACKAGE (P_D):

For $T_A = -55^\circ\text{C}$ to $+100^\circ\text{C}$ 500mW

For $T_A = +100^\circ\text{C}$ to $+125^\circ\text{C}$ Derate Linearity at 12mW/ $^\circ\text{C}$ to 200mW

DEVICE DISSIPATION PER OUTPUT TRANSISTOR

FOR $T_A =$ FULL PACKAGE-TEMPERATURE RANGE (All Package Types) 100mW

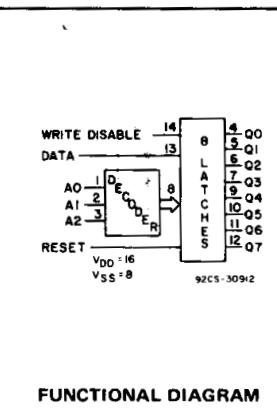
OPERATING-TEMPERATURE RANGE (T_A) -55°C to +125°C

STORAGE TEMPERATURE RANGE (T_{stg}) -65°C to +150°C

LEAD TEMPERATURE (DURING SOLDERING):

At distance $1/16 \pm 1/32$ inch (1.59 ± 0.79 mm) from case for 10s max +265°C

At distance $1/16 \pm 1/32$ inch (1.59 ± 0.79 mm) from case for 10s max +265°C



FUNCTIONAL DIAGRAM

Applications:

- Multi-line decoders
- A/D converters

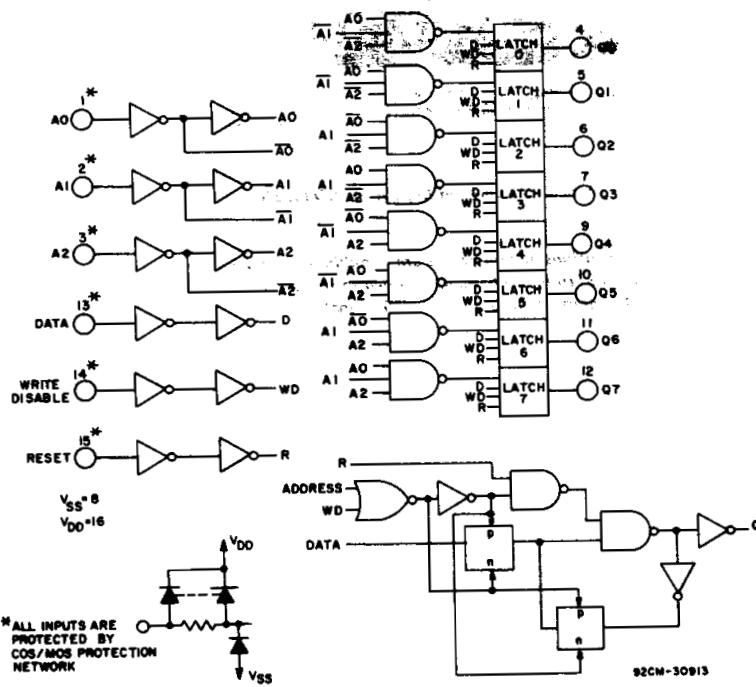
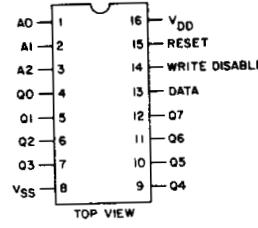


Fig. 1 – Logic diagram of CD4724B and detail of 1 of 8 latches.



TERMINAL ASSIGNMENT

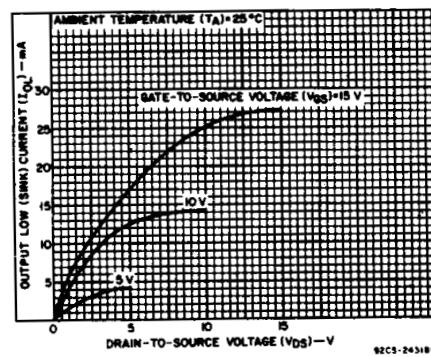


Fig. 2 – Typical output low (sink) current characteristics.

CD4724B Types

RECOMMENDED OPERATING CONDITIONS at $T_A = 25^\circ C$ (Unless otherwise specified)
 For maximum reliability, nominal operating conditions should be selected so that operation
 is always within the following ranges.

CHARACTERISTIC	SEE FIG. 15*	V _{DD} (V)	LIMITS		UNITS
			MIN.	MAX.	
Supply Voltage Range: (At $T_A = 25^\circ C$ Temperature Range)			3	18	V
Pulse Width, t_W Data	4	5	200	—	ns
		10	100	—	
		15	80	—	
Address	8	5	400	—	ns
		10	200	—	
		15	125	—	
Reset	5	5	150	—	ns
		10	75	—	
		15	50	—	
Setup Time, t_S Data to WRITE DISABLE	6	5	100	—	ns
		10	50	—	
		15	35	—	
Hold Time, t_H Data to WRITE DISABLE	7	5	150	—	ns
		10	75	—	
		15	50	—	

* Circled numbers refer to times indicated on master timing diagram.

Note: In addition to the above characteristics, a WRITE DISABLE ON time (the time that WRITE DISABLE is at a high level) must be observed during an address change for the total time that the external address lines A0, A1, and A2 are settling to a stable level, to prevent a wrong cell from being addressed.

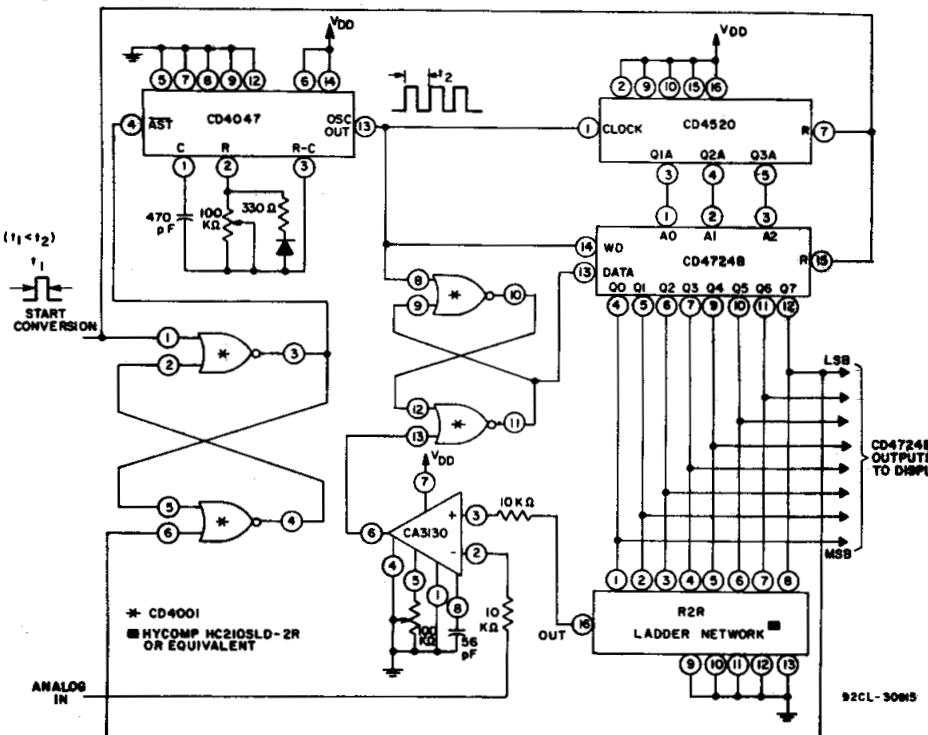


Fig. 5— A/D converter

MODE SELECTION			
WD	R	ADDRESSED LATCH	UNADDRESSED LATCH
0	0	Follows Data	Holds Previous State
0	1	Follows Data (Active High 8-Channel Demultiplexer)	Reset to "0"
1	0	Holds Previous State	
1	1	Reset to "0"	Reset to "0"

WD = WRITE DISABLE

R = RESET

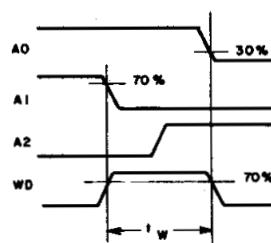


Fig. 3— Definition of WRITE DISABLE ON time.

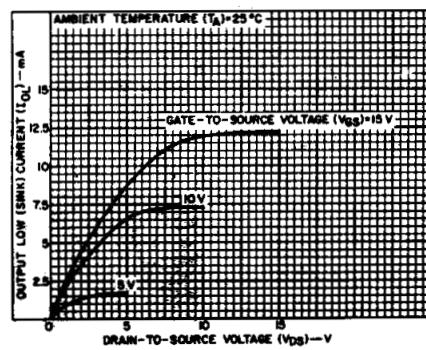


Fig. 4— Minimum output low (sink) current characteristics.

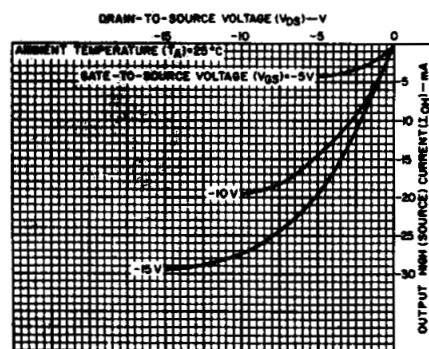
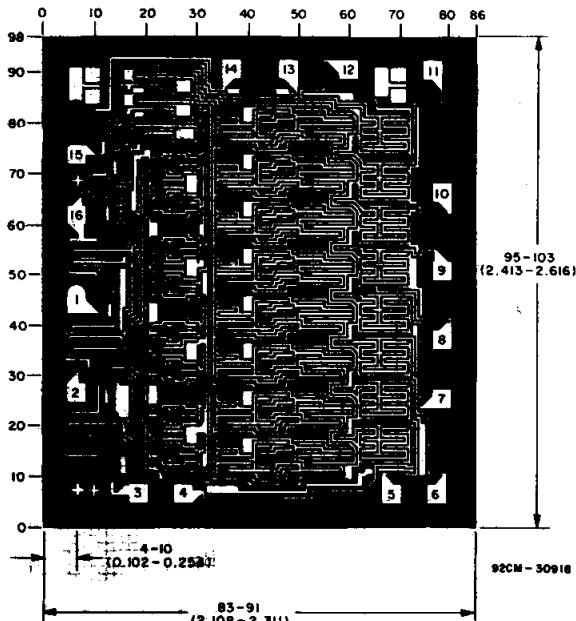


Fig. 6— Typical output high (source) current characteristics.

CD4724B Types

STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
				+25				Min.	Typ.	Max.	
	V_O (V)	V_{IN} (V)	V_{DD} (V)	-55	-40	+85	+125	Min.	Typ.	Max.	
Quiescent Device Current, I_{DD} Max.	-	0,5	5	5	5	150	150	-	0.04	5	μA
	-	0,10	10	10	10	300	300	-	0.04	10	
	-	0,15	15	20	20	600	600	-	0.04	20	
	-	0,20	20	100	100	3000	3000	-	0.08	100	
Output Low (Sink) Current I_{OL} Min.	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	-	mA
	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	-	
	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8	-	
Output High (Source) Current, I_{OH} Min.	4.6	0,5	5	-0.64	-0.61	-0.42	-0.36	-0.51	-1	-	mA
	2.5	0,5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	-	
	9.5	0,10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6	-	
	13.5	0,15	15	-4.2	-4	-2.8	-2.4	-3.4	-6.8	-	
Output Voltage: Low-Level, V_{OL} Max.	-	0,5	5	0.05				-	0	0.05	V
	-	0,10	10	0.05				-	0	0.05	
	-	0,15	15	0.05				-	0	0.05	
Output Voltage: High-Level, V_{OH} Min.	-	0,5	5	4.95				4.95	5	-	V
	-	0,10	10	9.95				9.95	10	-	
	-	0,15	15	14.95				14.95	15	-	
Input Low Voltage, V_{IL} Max.	0.5, 4.5	-	5	1.5				-	-	1.5	V
	1,9	-	10	3				-	-	3	
	1.5, 13.5	-	15	4				-	-	4	
Input High Voltage, V_{IH} Min.	0.5, 4.5	-	5	3.5				3.5	-	-	V
	1,9	-	10	7				7	-	-	
	1.5, 13.5	-	15	11				11	-	-	
Input Current I_{IN} Max.	-	0,18	18	± 0.1	± 0.1	± 1	± 1	-	$\pm 10^{-5}$	± 0.1	μA



CD4724BH
DIMENSIONS AND PAD LAYOUT

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

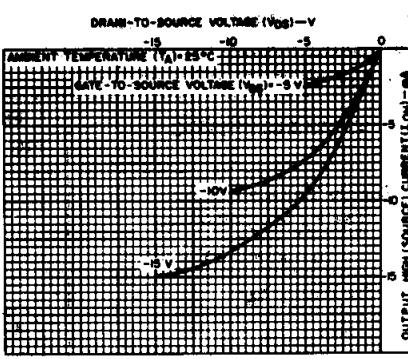


Fig. 7 - Minimum output high (source) current characteristics.

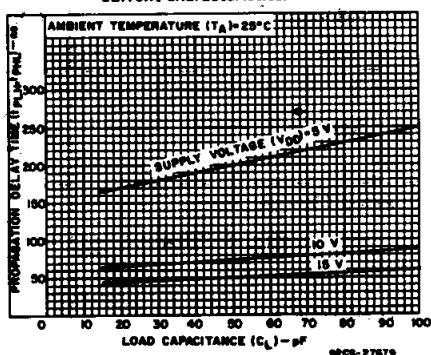


Fig. 8 - Typical propagation delay time (data to Q_n) vs. load capacitance.

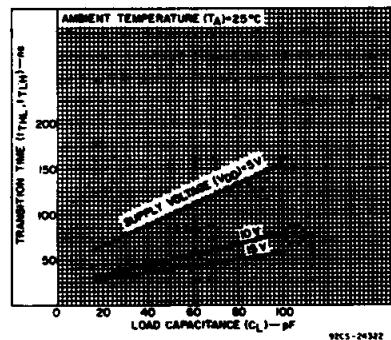


Fig. 9 - Typical transition time vs. load capacitance.

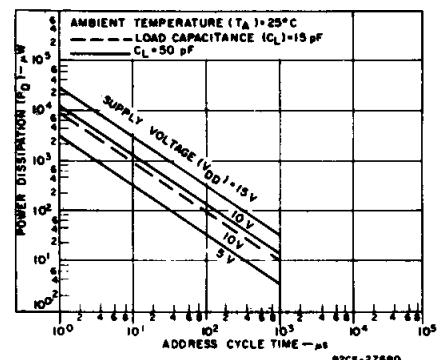


Fig. 10 - Typical dynamic power dissipation vs. address cycle time.

CD4724B Types

DYNAMIC ELECTRICAL CHARACTERISTICS at $T_A = 25^\circ C$, $C_L = 50 pF$,
 Input $t_r, t_f = 20 \text{ ns}$, $R_L = 200 \text{ k}\Omega$

CHARACTERISTIC	CONDITIONS		LIMITS ALL PACKAGE TYPES		UNITS
	SEE Fig. 15*	V_{DD} (V)	TYP.	MAX.	
Propagation Delay: t_{PLH} , t_{PHL} Data to Output,	①	5	200	400	ns
		10	75	150	
		15	50	100	
WRITE DISABLE to Output, t_{PLH} , t_{PHL}	②	5	200	400	ns
		10	80	160	
		15	60	120	
Reset to Output, t_{PHL}	③	5	175	350	ns
		10	80	160	
		15	65	130	
Address to Output, t_{PLH} , t_{PHL}	⑨	5	225	450	ns
		10	100	200	
		15	75	150	
Transition Time, t_{THL} (Any Output) t_{TLH}		5	100	200	ns
		10	50	100	
		15	40	80	
Minimum Pulse Width, t_W Data	④	5	100	200	ns
		10	50	100	
		15	40	80	
Address	⑧	5	200	400	ns
		10	100	200	
		15	65	125	
Reset	⑤	5	75	150	ns
		10	40	75	
		15	25	50	
Minimum Setup Time, t_S Data to WRITE DISABLE	⑥	5	50	100	ns
		10	25	50	
		15	20	35	
Minimum Hold Time, t_H Data to WRITE DISABLE	⑦	5	75	150	ns
		10	40	75	
		15	25	50	
Input Capacitance, C_{IN}	Any Input	5	7.5	pF	

*Circled numbers refer to times indicated on master timing diagram.

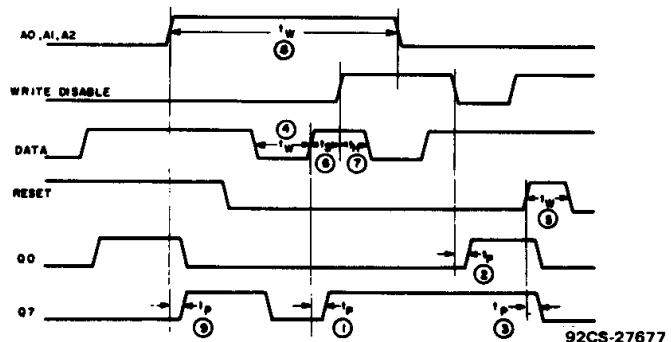


Fig. 15 - Master timing diagram.

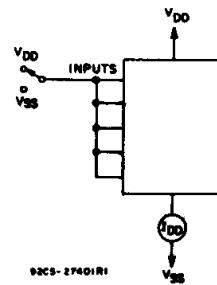


Fig. 11 - Quiescent device current test circuit.

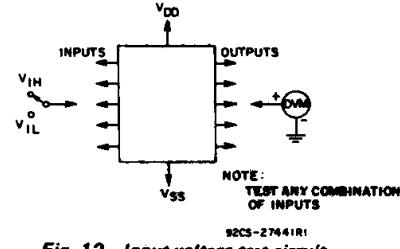


Fig. 12 - Input voltage test circuit.

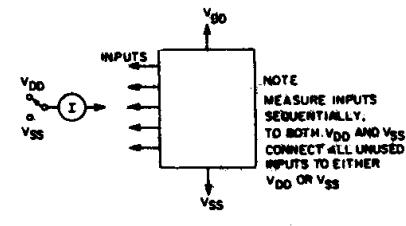


Fig. 13 - Input current test circuit.

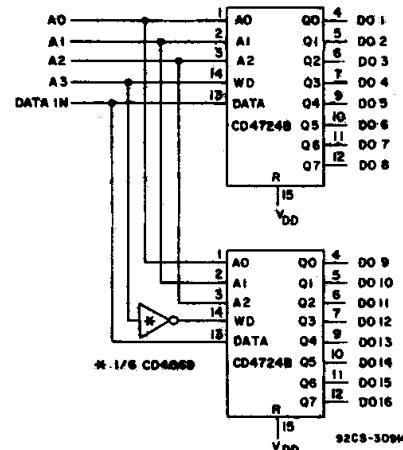


Fig. 14 - 1 of 16 decoder/demultiplexer.

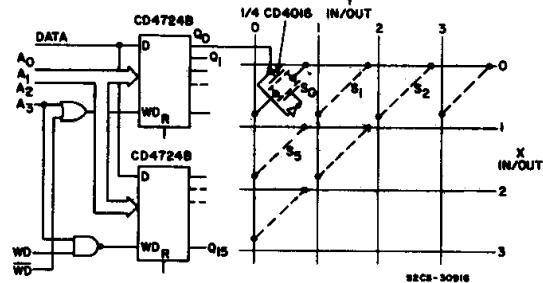


Fig. 16 - Multiple selection decoding - 4x4 crosspoint switch.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CD4724BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD4724BE	Samples
CD4724BEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-55 to 125	CD4724BE	Samples
CD4724BF3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	-55 to 125	CD4724BF3A	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF CD4724B, CD4724B-MIL :

- Catalog: [CD4724B](#)
- Military: [CD4724B-MIL](#)

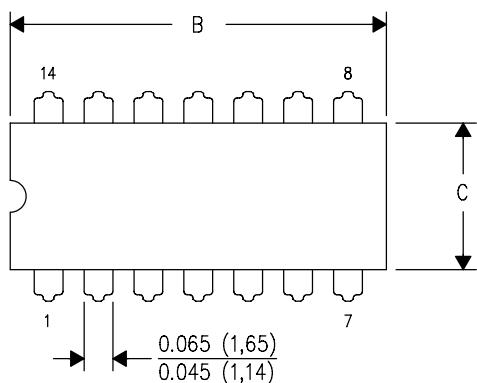
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- Military - QML certified for Military and Defense Applications

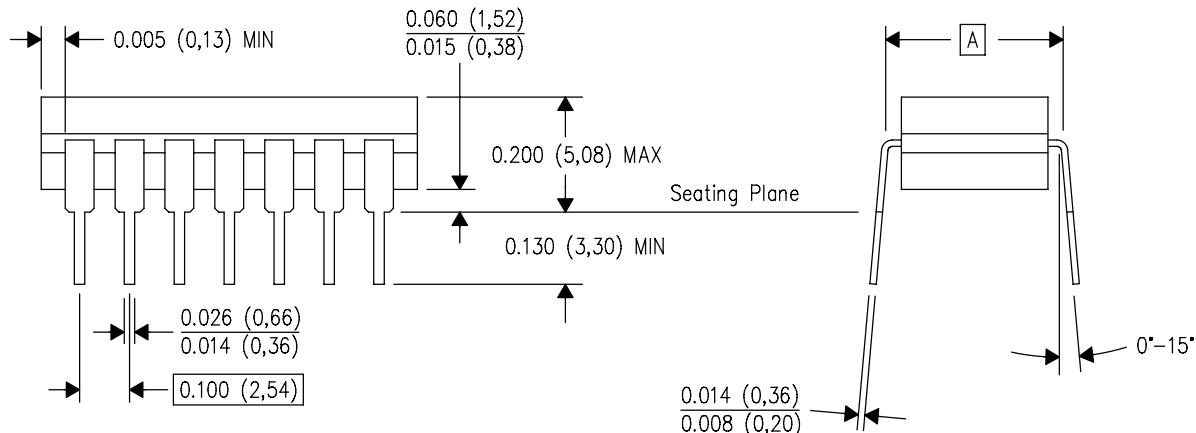
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



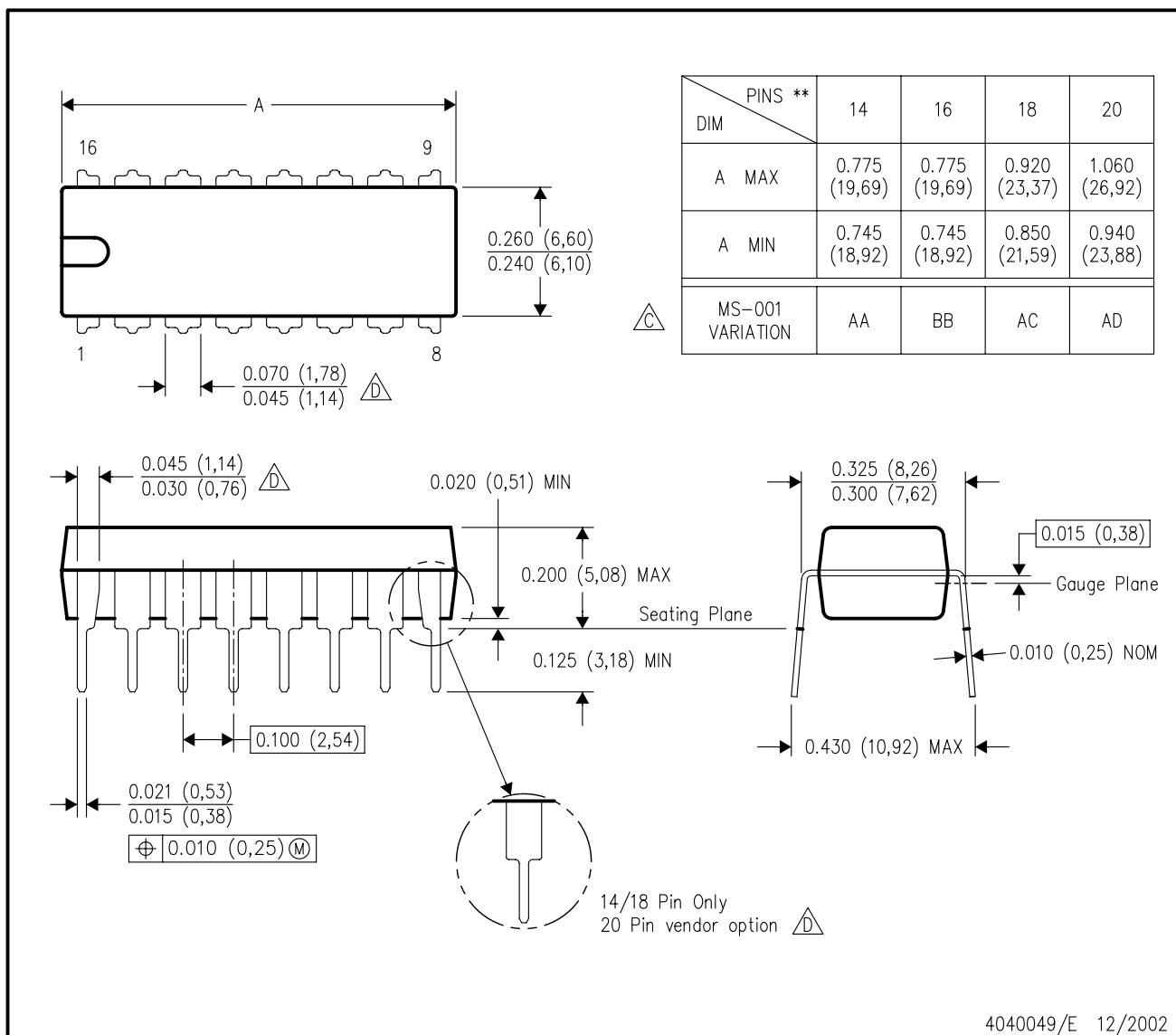
4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.

△ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

△ The 20 pin end lead shoulder width is a vendor option, either half or full width.

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RFID	www.ti-rfid.com
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Wireless Connectivity	www.ti.com/wirelessconnectivity
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